

## 650V N-Channel Power MOSFET

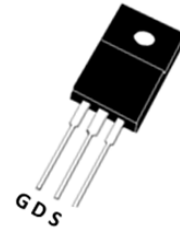
### DESCRIPTION :

- Fast Switching Capability
- Extremely Low Gate Charge
- 100% UIS Tested, 100% Rg Tested
- Fast Recovery Body Diode
- RoHS compliant
- Pb-Free Lead Plating

$V_{DSS}$	650V
$I_D @ V_{GS}=10V$	20A
$R_{DS(ON)_Typ.} @ V_{GS}=10V$	170m $\Omega$

### TYPICAL APPLICATIONS :

- Telecom / Server Power Supplies
- Industrial Power Supplies
- Lighting / Charger / Adapter
- UPS / Solar



ITO-220AB

### MAXIMUM RATINGS (at $T_A = 25^\circ\text{C}$ , unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	650	V
Gate-Source Voltage		$V_{GS}$	$\pm 30$	V
Continuous Drain Current	$T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	$I_D$	20 13	A
Pulsed Drain Current <sup>(1)</sup>		$I_{DM}$	75	A
Avalanche Current <sup>(2)</sup>		$I_{AS}$	9	A
Avalanche Energy <sup>(2)</sup>		$E_{AS}$	405	mJ
Power dissipation	$T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	$P_D$	36 14.3	W
Junction & Storage temperature Range		$T_J, T_{STG}$	-55~+150	$^\circ\text{C}$

Notes : 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. The single-pulse measurement was taken under the following condition [ $V_{DS}=50V, V_{GS}=10V, L=10\text{mh}$ ] while its value is limited by  $T_{JMAX} = 150^\circ\text{C}$

### THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Value	Unit
Thermal resistance,	Junction to Ambient Junction to Case	$R_{\theta JA}$ $R_{\theta JC}$	62 4.2	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage VGS = 0V, ID = 250uA	$V_{(BR)DSS}$	650			V
Zero Gate Voltage Drain Current VDS = 650 V, VGS = 0 V	$I_{DSS}$			1	uA
Gate-Source Leakage Current VGS = $\pm 30$ V, VDS = 0V	$I_{GSS}$			$\pm 100$	nA
Gate-Source threshold voltage VDS = VGS, ID = 250uA	$V_{GS(th)}$	2.5	3.5	4.5	V
Drain-Source On-State Resistance VGS = 10V, ID = 10A	$R_{DS(on)}$		170	190	m $\Omega$
Input capacitance f=1MHz, VDS=100 V, VGS=0 V	$C_{iss}$		1560		pF
Output capacitance f=1MHz, VDS=100 V, VGS=0 V	$C_{oss}$		61		pF
Reverse transfer capacitance f=1MHz, VDS=100 V, VGS=0 V	$C_{rss}$		11.7		pF
Gate Resistance VDS=0 V, VGS= 0V, f=1MHz	$R_g$		8.9		$\Omega$
Total Gate Charge VDS= 325V, ID= 10A, VGS=0 to 10V	$Q_G$		38		nC
Gate to Source Charge VDS= 325V, ID= 10A, VGS=0 to 10V	$Q_{GS}$		10.1		nC
Gate to Drain Charge VDS= 325V, ID= 10A, VGS=0 to 10V	$Q_{GD}$		14.8		nC
Turn-on delay time VDS=325 V, VGS= 10V, $R_L=32.5\Omega$ , $R_{GEN}=6\Omega$	$t_{d(ON)}$		17.8		ns
Rise time VDS=325 V, VGS= 10V, $R_L=32.5\Omega$ , $R_{GEN}=6\Omega$	$t_r$		22		ns
Turn-off delay time VDS=325 V, VGS= 10V, $R_L=32.5\Omega$ , $R_{GEN}=6\Omega$	$t_{d(OFF)}$		257		ns
Fall time VDS=325 V, VGS= 10V, $R_L=32.5\Omega$ , $R_{GEN}=6\Omega$	$t_f$		20		ns

## Body Diode

ELECTRICAL CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Diode Forward Voltage $V_{GS} = 0V, I_S = 1A$	$V_{SD}$		0.75	1.0	V
Diode Continuous Current, $T_c=25^\circ\text{C}$	$I_S$			36	A
Revers Recovery Time $I_F=10A, dI_F/dt = 100A/us$	$T_{rr}$		120		ns
Revers Recovery Charge $I_F=10A, dI_F/dt = 100A/us$	$Q_{rr}$		4.5		nC

Typical Performance Characteristics

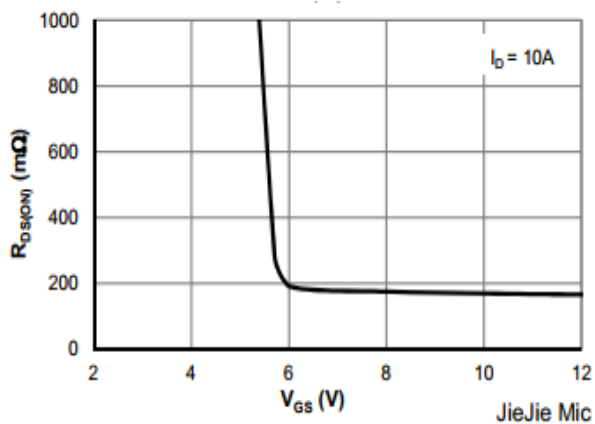


Figure 1.  $R_{DS(ON)}$  vs.  $V_{GS}$

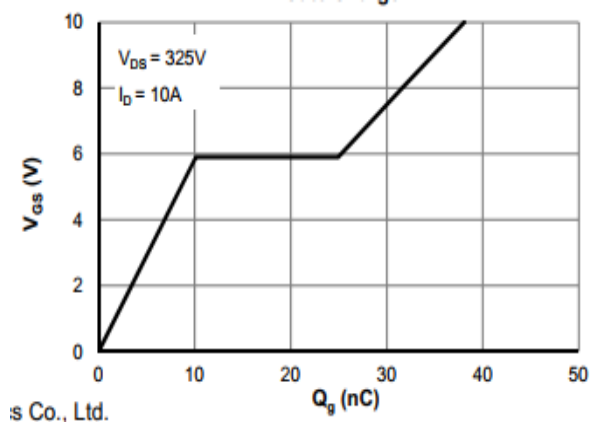


Figure 2. Gate Charge Characteristics

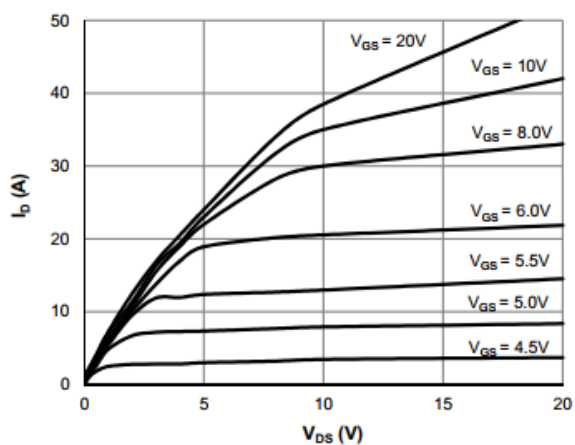


Figure 3. Saturation Characteristics

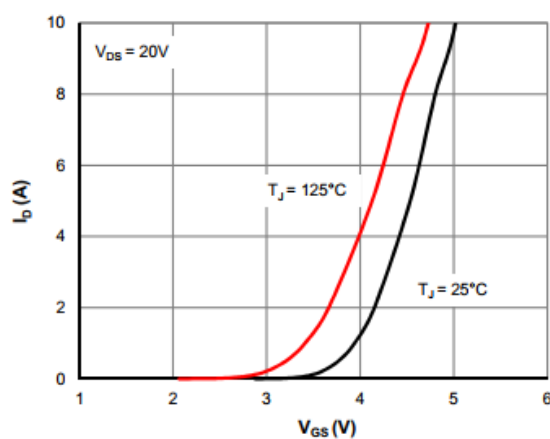


Figure 4. Transfer Characteristics

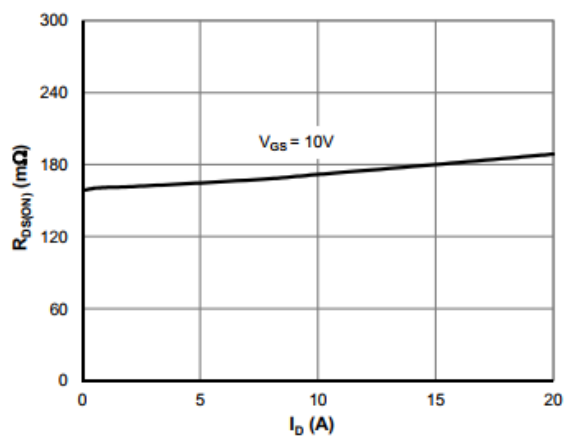


Figure 5. On-resistance vs. Drain Current

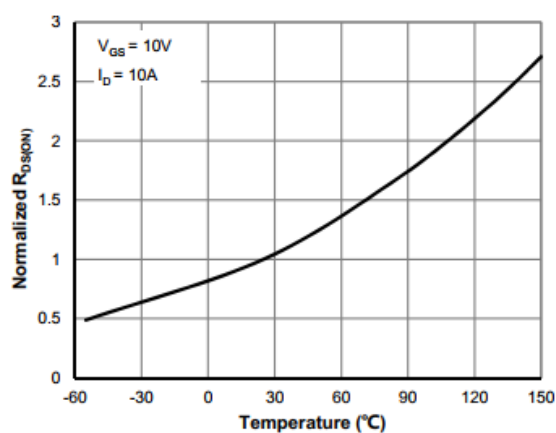


Figure 6.  $R_{DS(ON)}$  vs. Junction Temperature

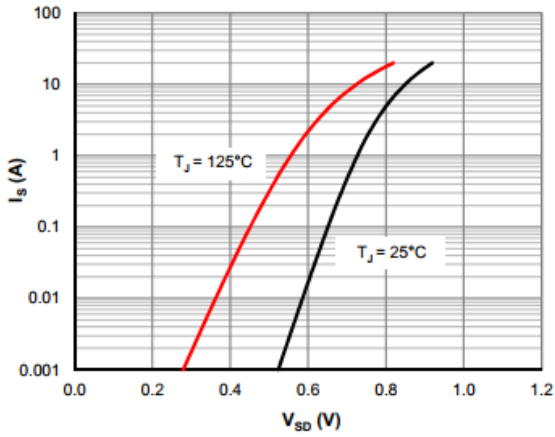


Figure 7. Body-Diode Characteristics

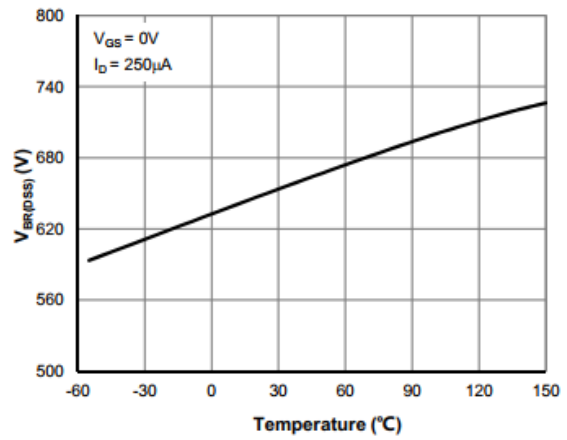


Figure 8.  $V_{BR(DSS)}$  vs. Junction Temperature

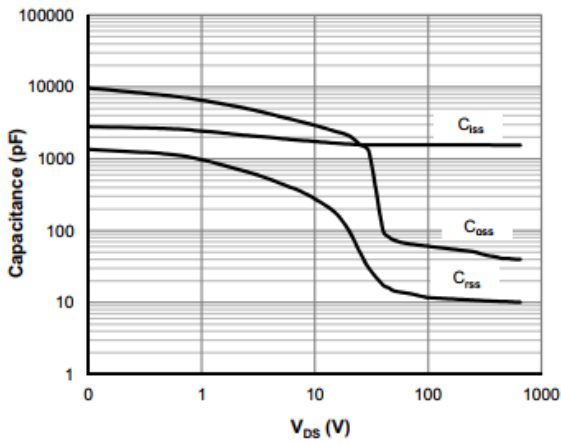


Figure 9. Capacitance Characteristics

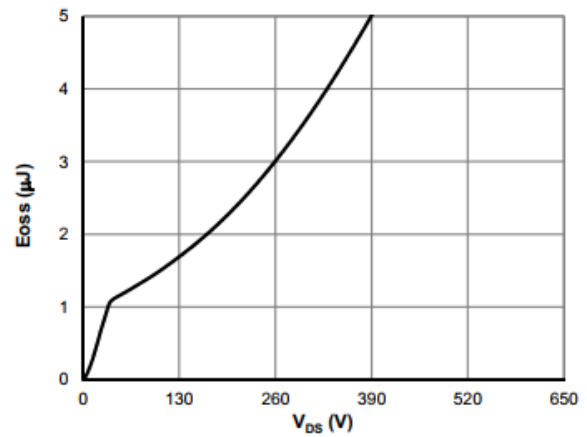


Figure 10.  $C_{oss}$  Stored Energy

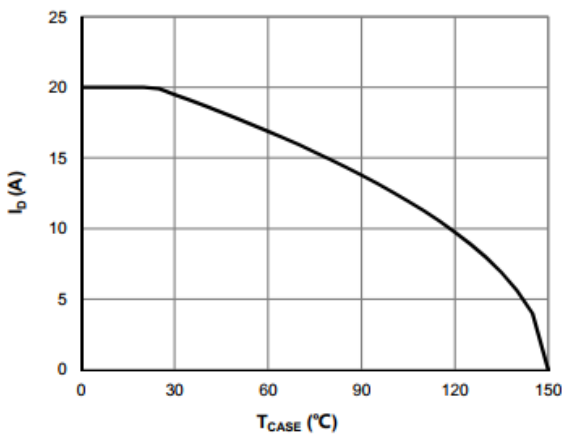


Figure 11. Current De-rating

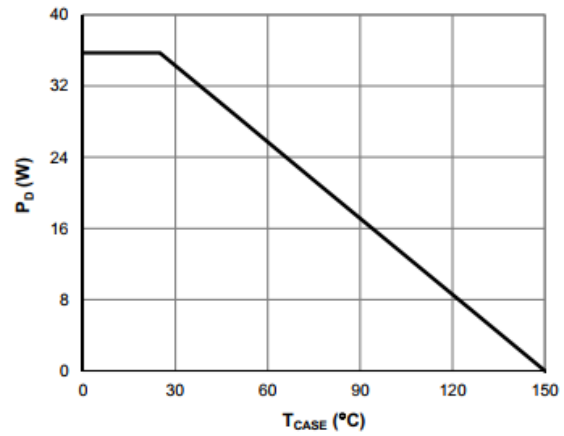


Figure 12. Power De-rating

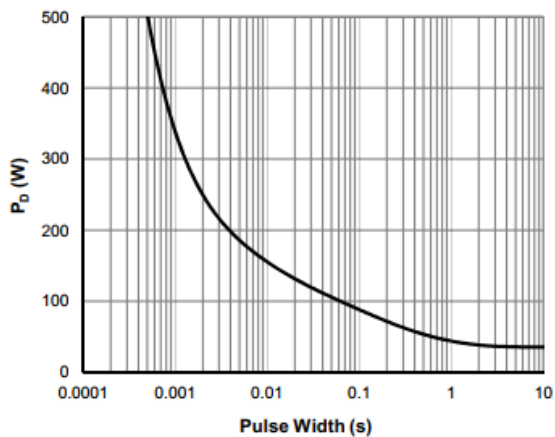


Figure 13. Single Pulse Power Rating, Junction-to-Case

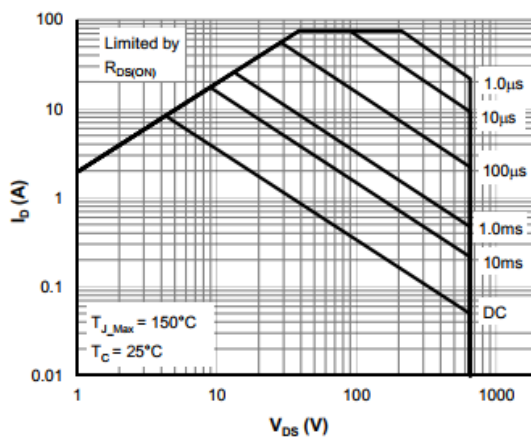


Figure 14. Maximum Safe Operating Area

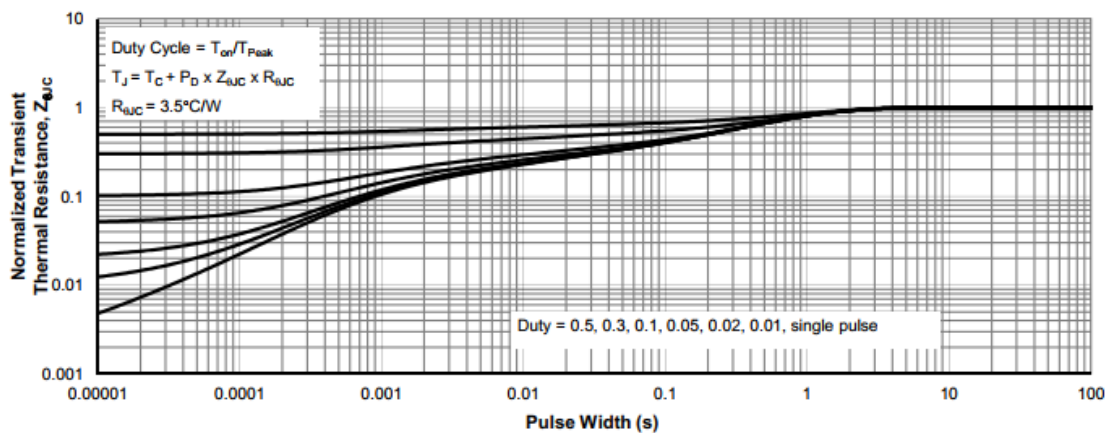
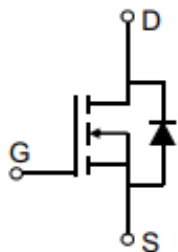
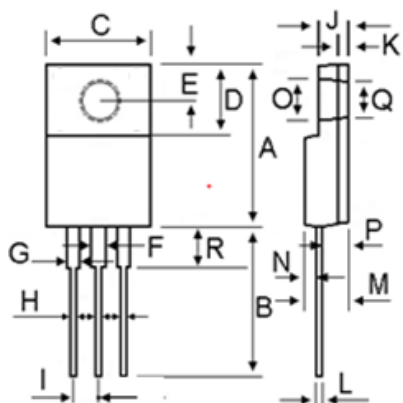


Figure 15. Normalized Maximum Transient Thermal Impedance

- Circuit diagram



- Package outlines :



DIM	MILLIMETERS	
	MIN	MAX
A	14.80	16.10
B	12.65	14.40
C	9.70	10.36
D	4.60	6.80
E	2.50	3.50
F	0.90	1.55
G	0.90	1.55
H	0.50	0.90
I	2.40	2.70
J	2.34	3.30
K	0.55	1.30
L	0.36	0.80
M	4.20	4.90
N	1.10	1.80
O	2.90	3.50
P	2.30	3.15
Q	2.90	3.50
R	2.80	4.85

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